

Title (en)
METHOD FOR PRODUCING FULL CERAMIC SUBSTRUCTURES, ESPECIALLY CONSISTING OF ALUMINA, IN DENTISTRY

Title (de)
VERFAHREN ZUR HERSTELLUNG VOLLKERAMISCHER GERÜSTEN IN DER ZAHNTECHNIK, INSBESONDERE AUS ALUMINA

Title (fr)
PROCEDE DE PRODUCTION DE SOUS-STRUCTURES EN CERAMIQUE PLEINE, NOTAMMENT EN ALUMINE, EN TECHNIQUE DENTAIRE

Publication
EP 1280475 A1 20030205 (DE)

Application
EP 01933815 A 20010407

Priority

- DE 10021437 A 20000503
- EP 0104132 W 20010407

Abstract (en)
[origin: WO0185053A1] The invention relates to the production of substructures, especially copings, consisting of ceramic material, preferably alumina. The stump of a work model is lined with a film or a separating agent. This lining is made electroconductive by e.g. using a metallized film or applying a silver coating. The stump is dipped in slip and a direct voltage is applied, causing the stump to be coated with an even ceramic, e.g. alumina layer which can be baked into a ceramic blank immediately after drying. The resistance of said ceramic blank is then increased by glass infiltration. Post-processing is not necessary since the ceramic material is deposited with a very even layer thickness. The inventive method is associated with a considerable saving of time in the production of a full ceramic tooth replacement.

IPC 1-7
A61C 13/00; **A61C 5/10**; **C25D 1/14**

IPC 8 full level
A61C 5/77 (2017.01); **A61C 13/00** (2006.01); **C25D 1/14** (2006.01); **C25D 1/20** (2006.01); **A61C 13/083** (2006.01)

CPC (source: EP US)
A61C 5/77 (2017.01 - EP US); **A61C 13/0003** (2013.01 - EP US); **A61C 13/001** (2013.01 - EP US); **C25D 1/14** (2013.01 - EP US); **C25D 1/20** (2013.01 - EP US); **A61C 13/0835** (2013.01 - EP US)

Citation (search report)
See references of WO 0185053A1

Cited by
DE102011116255B3; WO2013056970A2

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)
WO 0185053 A1 20011115; AT E276711 T1 20041015; AU 6019601 A 20011120; DE 10021437 A1 20011115; DE 10021437 C2 20020508; DE 50103769 D1 20041028; DK 1280475 T3 20050124; EP 1280475 A1 20030205; EP 1280475 B1 20040922; ES 2225540 T3 20050316; US 2004026806 A1 20040212

DOCDB simple family (application)
EP 0104132 W 20010407; AT 01933815 T 20010407; AU 6019601 A 20010407; DE 10021437 A 20000503; DE 50103769 T 20010407; DK 01933815 T 20010407; EP 01933815 A 20010407; ES 01933815 T 20010407; US 36334403 A 20030303